## BT134W series E

### **GENERAL DESCRIPTION**

Glass passivated, sensitive gate triacs in a plastic envelope suitable for surface mounting, intended for use in general purpose bidirectional switching and phase control applications, where high sensitivity is required in all four quadrants.

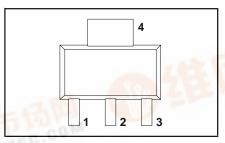
### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
V <sub>DRM</sub> I <sub>T(RMS)</sub> I <sub>TSM</sub>	Repetitive peak off-state voltages RMS on-state current Non-repetitive peak on-state current	<b>500E</b> 500 1 10	<b>600E</b> 600 1 10	V A A

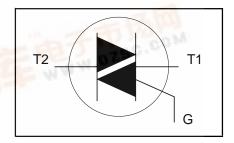
## **PINNING - SOT223**

PIN	DESCRIPTION		
1	main terminal 1		
2	main terminal 2		
3	gate		
tab	main terminal 2		

## **PIN CONFIGURATION**



## **SYMBOL**



### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

WWW.DZSC

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>DRM</sub>	Repetitive peak off-state voltages	1670	É	<b>-500 -600</b> 600 <sup>1</sup>	V
I <sub>T(RMS)</sub>	RMS on-state current Non-repetitive peak on-state current	full sine wave; T <sub>sp</sub> ≤ 108 °C full sine wave; T <sub>j</sub> = 25 °C prior to surge	1-5	1	А
	- T	t = 20 ms	-	10	A
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t = 16.7 ms t = 10 ms	-	11 0.5	A A <sup>2</sup> s
dl <sub>⊤</sub> /dt	Repetitive rate of rise of on-state current after	$I_{TM} = 1.5 \text{ A}; I_{G} = 0.2 \text{ A}; \\ dI_{G}/dt = 0.2 \text{ A}/\mu\text{s}$	_	0.5	A 5
0 //((b)	triggering	T2+ G+	-	50	A/μs
The state of		T2+ G-	-	50	A/μs
		T2- G- T2- G+		50 10 - 5 G - C O	A/μs
I <sub>GM</sub>	Peak gate current	12- 9+		2	A/μs   A
V <sub>GM</sub>	Peak gate voltage	- LT		5	V
$P_{GM}$	Peak gate power		-	5 5	W
	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- -40 -	0.5 150 125	°C °C

BT134W series E

## THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-sp</sub>	Thermal resistance iunction to solder point	full or half cycle	1	1	15	K/W
R <sub>th j-a</sub>	Thermal resistance junction to ambient	pcb mounted; minimum footprint pcb mounted; pad area as in fig:14	-	156 70	-	K/W K/W

## STATIC CHARACTERISTICS

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>GT</sub>	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$				
01		T2+ G+	-	2.5	10	mA
		T2+ G-	-	4.0	10	mA
		T2- G-	-	5.0	10	mA
		T2- G+	-	11	25	mA
I <sub>L</sub>	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$				
		T2+ G+	-	3.0	15	mA
		T2+ G-	-	10	20	mA
		<u>T2- G</u> -	-	2.5	15	mA.
		T2- G+	-	4.0	20	mA
l I <sub>H</sub>	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	2.2	15	mΑ
I <sub>H</sub> V <sub>T</sub>	On-state voltage	$I_T = 2 A$	-	1.2	1.5	V
V <sub>GT</sub>	Gate trigger voltage	$\dot{V}_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$	-	0.7	1.5	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_i = 125 ^{\circ}\text{C}$	0.25	0.4	-	V .
$I_{D}$	Off-state leakage current	$V_D = V_{DRM(max)}$ ; $T_j = 125$ °C	-	0.1	0.5	mA

## **DYNAMIC CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV <sub>D</sub> /dt	Critical rate of rise of	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$	-	30	-	V/μs
t <sub>gt</sub>	off-state voltage Gate controlled turn-on time	exponential waveform; gate open circuit $I_{TM} = 1.5 \text{ A}$ ; $V_D = V_{DRM(max)}$ ; $I_G = 0.1 \text{ A}$ ; $dI_G/dt = 5 \text{ A}/\mu\text{s}$	-	2	-	μs

BT134W series E

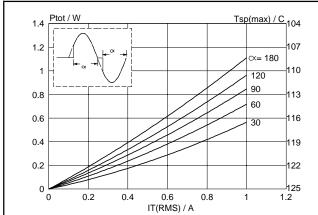


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus rms on-state current,  $I_{T(RMS)}$ , where  $\alpha$  = conduction angle.

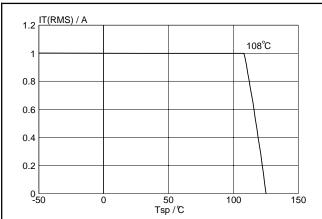


Fig.4. Maximum permissible rms current  $I_{T(RMS)}$ , versus solder point temperature  $T_{\rm sp}$ .

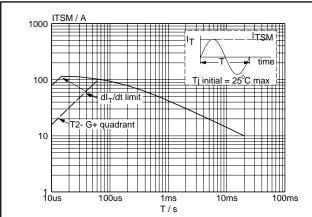


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \le 20$ ms.

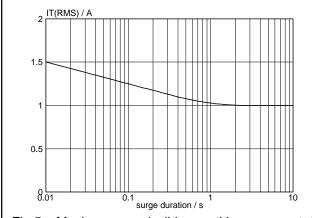


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents, f = 50 Hz;  $T_{sp} \le 108$  °C.

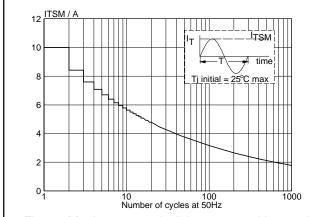


Fig.3. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents, f = 50 Hz.

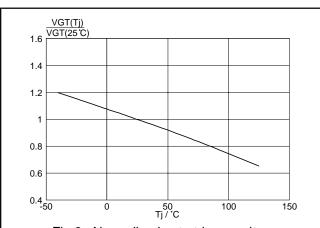
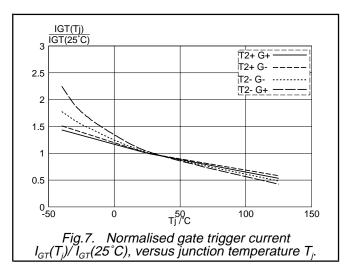
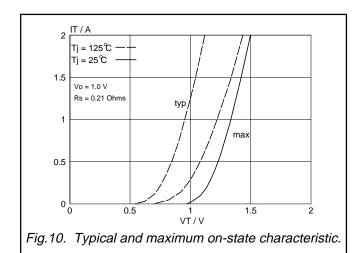
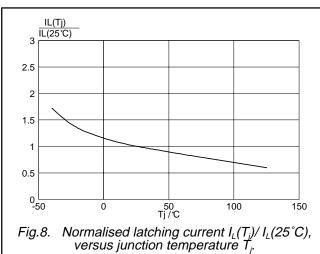


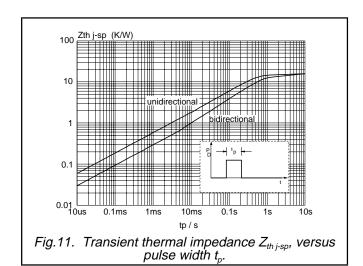
Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$ , versus junction temperature  $T_{j\cdot}$ 

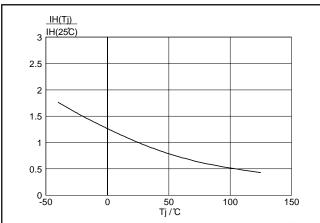
BT134W series E











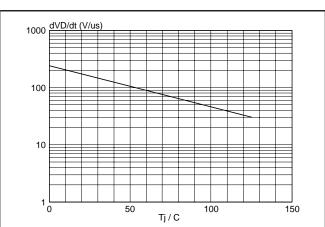
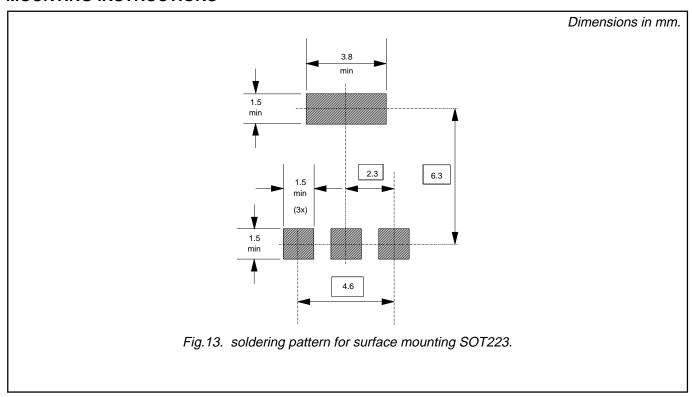


Fig.9. Normalised holding current  $I_H(T_i)/I_H(25^{\circ}C)$ , versus junction temperature  $T_i$ .

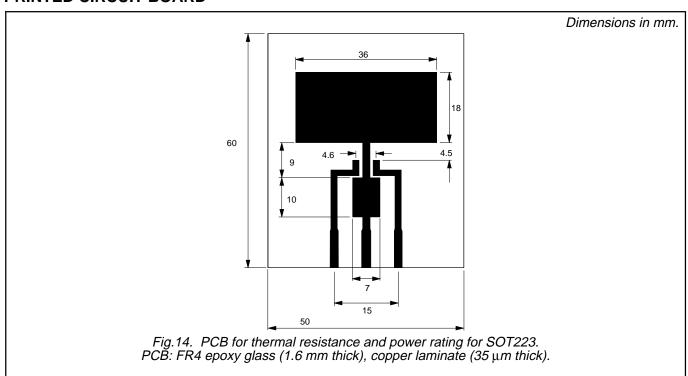
Fig.12. Typical, critical rate of rise of off-state voltage,  $dV_D/dt$  versus junction temperature  $T_{j\cdot}$ 

BT134W series E

## **MOUNTING INSTRUCTIONS**

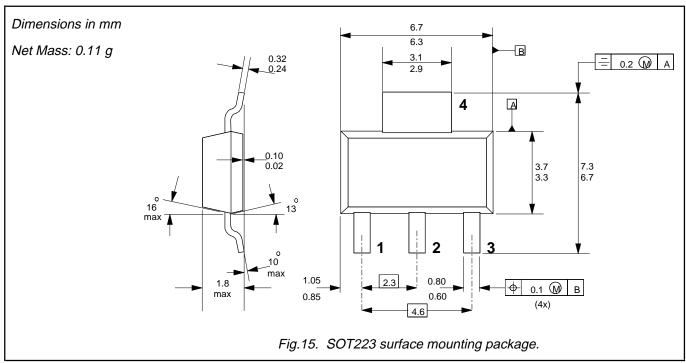


## **PRINTED CIRCUIT BOARD**



BT134W series E

## **MECHANICAL DATA**



### **Notes**

- For further information, refer to Philips publication SC18 " SMD Footprint Design and Soldering Guidelines".
   Order code: 9397 750 00505.
   Epoxy meets UL94 V0 at 1/8".

BT134W series E

#### **DEFINITIONS**

Data sheet status				
Objective specification This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
1				

### Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

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